

AMENDMENTS TO THE ABSTRACT

Please amend the Abstract as follows:

~~The present invention discloses a~~A light emitting device package, ~~comprising~~includes a metal ~~base; base~~, an electrical circuit layer provided at an upper side of the metal base for providing a conductive ~~path; path~~, a light emitting device mounted in a second region having a smaller thickness than a first region on the metal ~~base; base~~, an insulating layer sandwiched between the ~~meta-metal~~ base and the electrical circuit ~~layer; layer~~, an electrode layer provided at an upper side of the electrical circuit ~~layer; layer~~, and a wire for electrically connecting the electrode layer and the light emitting device. ~~Further, there is provided a~~The light emitting device package ~~which is improved in~~has improved light emission efficiency since the light emitting device is placed on a small thickness portion of the metal base.